## In the United States Patent and Trademark Office

Serial Number: Appn. Filed: Toshio Havakawa Applicant:

Appn Title: A Staff Sheet Printer

Examiner/GAU: Jeffrey Donels/2837

Mailed 2002, January 29

Request for File-Wrapper-Continuing Application Box: FWC **Assistant Commissioner to Patents** Washington, District of Columbia 20231 Sir: Pursuant to Rule 62, please file a file-wrapper-continuing application of the above pending complete application. This Rule 62 continuing application is being actually filed in the PTO or express mailed during the pendency of the above application. It should be a  $\square$  Continuation-in Part  $\square$  Division  $\boxtimes$  Continuation of the above application. Please use the specification (including the claims and abstract) of the above application and also use The Declaration therefrom if this is a Continuation or Division. Enclosed is a Preliminary Amendment for this Rule 62 Application. Please enter the Amendment Under Rule 116 in the parent application. Enclosed is a new Declaration if this is a CIP application. Please use  $\square$  the drawings of the above application  $\boxtimes$  the new drawing(s) enclosed (  $\underline{6}$  \_\_\_\_\_ sheets). After entry of this Preliminary Amendment (or any Amendments under Rule 116 in the above application) there will be not more than 3 independent and 20 total claims. A small entity declaration  $\square$  was enclosed for the above application \( \sigma \) is enclosed. Thus the filing fee for the Rule 62 Application will be \$ 370; a check for this amount is enclosed. Very Respectfully, Applicant: Toshio Hayakawa Enc. (s): Filing Fee: Also New Declaration and /or Amendment, if indicated Tel: (310) 836-3540 Express Mail Label #:ET527183836US Date of Deposit: 2002, January 29 I hereby certify that this paper or fee being deposited with the United States Postal Service Using "Express Mail

Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to "BOX, FWC Assistant Commissioner for Patents, Washington, DC 20231."